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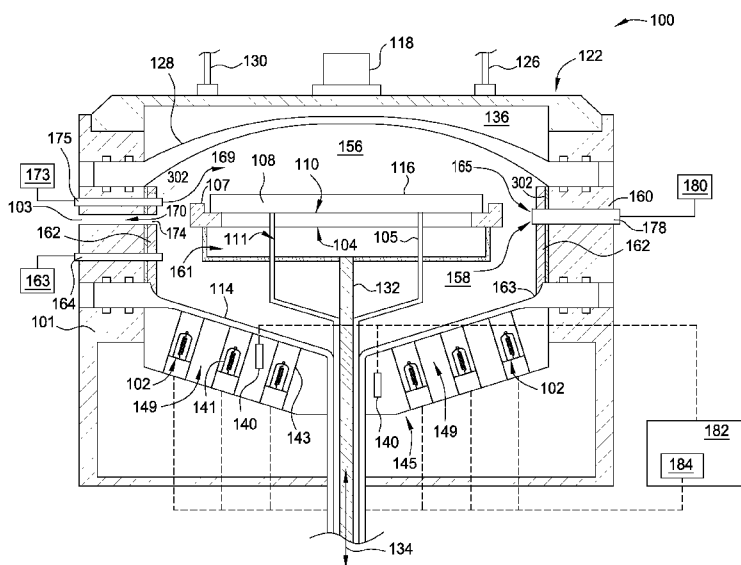


FIG. 1

(57) Abstract: Embodiments disclosed herein relate to coated liner assemblies for use in a semiconductor processing chamber. In one embodiment, a liner assembly for use in a semiconductor processing chamber includes a liner body having a cylindrical ring form and a coating layer coating the liner body, wherein the coating layer is opaque at one or more wavelengths between about 200 nm and about 5000 nm. In another embodiment, an apparatus for depositing a dielectric layer on a substrate includes a processing chamber having an interior volume defined in a chamber body of the processing chamber, a liner assembly disposed in the processing chamber, wherein the liner assembly further comprises a liner body having a cylindrical ring form, and a coating layer coating an outer wall of the liner body and facing the chamber body, wherein the coating layer is opaque at one or more wavelengths between about 200 nm and about 5000 nm.